

What is claimed is:

Sub a1/ 1.

A semiconductor wafer grinding method, comprising:

grinding a semiconductor wafer by fixed abrasive grains; and

continuously grinding the semiconductor wafer by free abrasive grains.

2. The semiconductor wafer grinding method according to claim 1, wherein:

grinding by fixed abrasive grains includes rough grinding using large diameter abrasive grains; and

grinding by free abrasive grains includes finish grinding using small diameter abrasive grains.

Sub a2 3.

The semiconductor wafer grinding method according to claim 1, wherein grinding includes both side grinding of a semiconductor wafer or grinding of a chamfered portion.

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